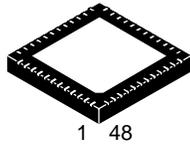


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

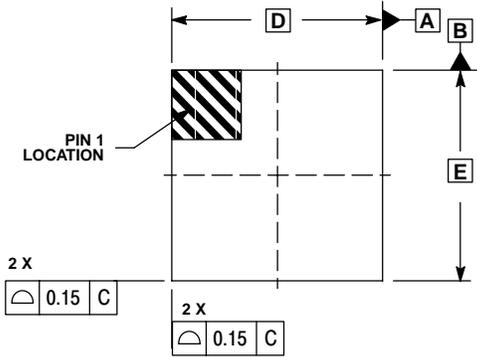
ON Semiconductor®



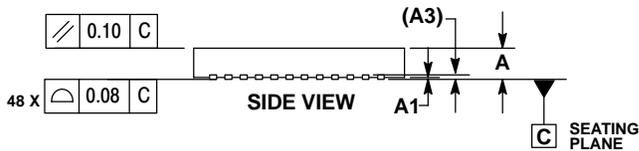
SCALE 2:1

QFN48
CASE 485K-02
ISSUE C

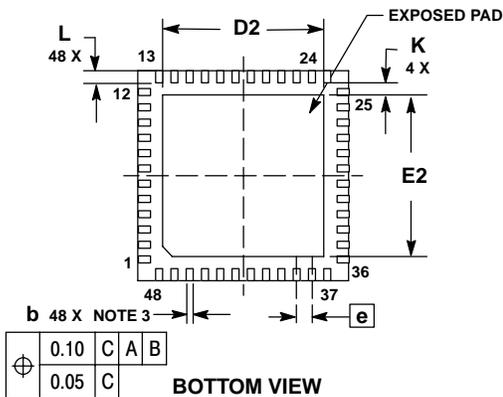
DATE 20 JUL 2004



TOP VIEW



SIDE VIEW



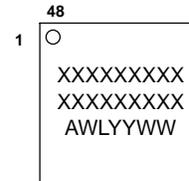
BOTTOM VIEW

NOTES:

- DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
- DIMENSIONS IN MILLIMETERS.
- DIMENSION b APPLIES TO THE PLATED TERMINAL AND IS MEASURED ABETWEEN 0.25 AND 0.30 MM FROM TERMINAL
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.800	0.900	1.000
A1	0.000	0.025	0.050
A3	0.200 REF		
b	0.180	0.250	0.300
D	7.000 BSC		
D2	5.260	5.360	5.460
E	7.000 BSC		
E2	5.260	5.360	5.460
e	0.500 BSC		
K	0.200	-----	-----
L	0.300	0.400	0.500

GENERIC MARKING DIAGRAM*



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "C" or microdot "•", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	48 PIN QFN, 7X7 MM 0.50 MM PITCH	PAGE 1 OF 2

